

Shenzhen 7SEtronic Semiconductor Co., Ltd

Components + PCBA Solutions



In collaboration with qualified manufacturing partners



Components Supply

Global sourcing
& BOM support



PCB Assembly

SMT / DIP / Testing
Box Build



Flexible Production

Prototype
to Mass Production



Quality Assurance

Inspection & Testing
Traceability Control

One contact for components sourcing
and manufacturing coordination.

Introduction

01: Sales Department

02: Factory Scale

03: Equipment Scale

04: Service Scope

05: Process Capabilities

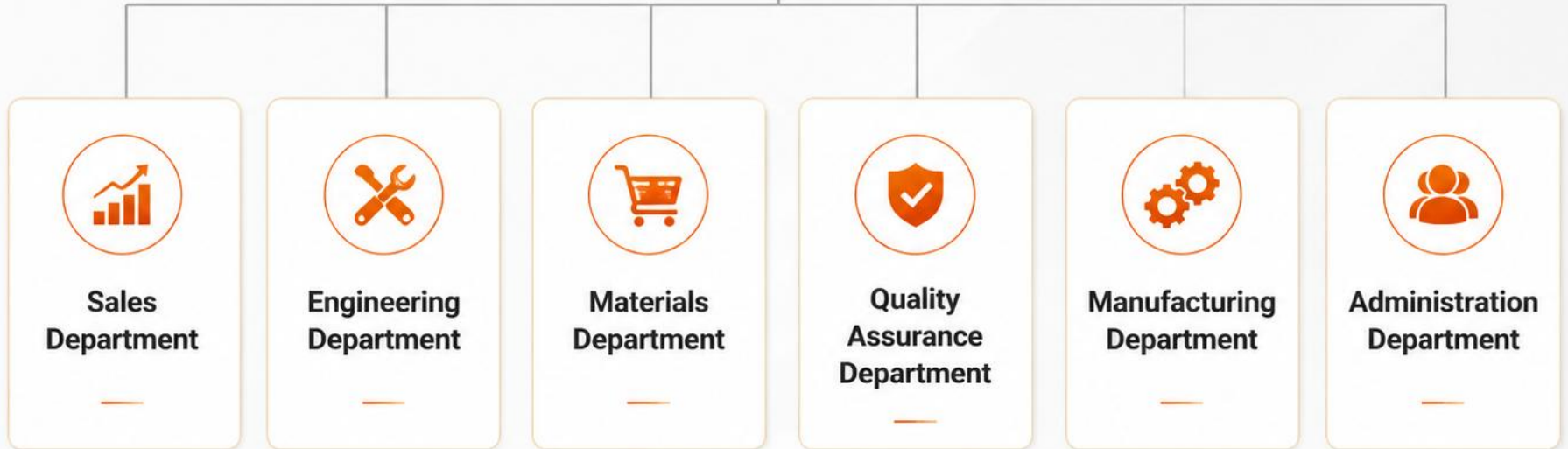
06: Application Areas

07: Our Advantages

08: Contact Us

01. Department Overview

Our professional teams work together to deliver high-quality products and services.



02、 Factory Scale

- Registered capital of RMB 5 million, with a 3,500 m² facility including SMT workshop, soldering workshop, testing workshop, assembly workshop, and warehouse.
- Equipped with 7 SMT production lines, wave soldering, fully automatic printing machines, 10-zone JT reflow soldering systems, and other advanced equipment.
- Equipped with precision inspection equipment such as AOI, SPI, and first article inspection systems to ensure product quality during production.



03、 Equipment Scale

Primary Production Equipment

NO.	Equipment	Brand	Model	Quantity	Process Capability	Production Speed / Capacity
1	High-Speed SMT Pick-and-Place Machine	YAMAHA	F8S, 4-Head Configuration	2 units	Component range: 0201–33 mm PCB size: 510 × 381 mm	150,000CPH
2	High-Speed Multi-Function Pick-and-Place Machine	YAMAHA	G5S, 2-Head Configuration	1 unit	Component range: 03015–large components PCB size: 1200 × 510 mm	75,000CPH
3	High-Speed Multi-Function Pick-and-Place Machine	YAMAHA	YSM10	6 units	Component range: 03015–55 × 100 mm PCB size: 510 × 460 mm	46,000CPH
4	High-Speed SMT Pick-and-Place Machine	YAMAHA	YSM20R	6 units	Component range: 0201–55 × 100 mm PCB size: 810 × 490 mm	95,000CPH

03、Equipment Scale

Primary Production Equipment

NO.	Equipment	Brand	Model	Quantity	Process Capability	Production Speed / Capacity
1	Fully Automatic Solder Paste Printer	德森	1008	7 units	0.3 mm pitch IC, 01005 and above chip components (R/C) PCB size: 460 × 340 mm	/
2	Reflow Soldering Oven	劲拓	10-Zone Dual-Lane	2 units	Lead-Free, 10 Top / 10 Bottom (20-Zone Total)	/
3	Reflow Soldering Oven	劲拓	8-Zone	1 unit	Lead-Free, 8 Upper / 8 Lower (16 Zones Total)	/
4	Wave Soldering Machine	HB,双波峰无铅波峰炉	HBE-350	1 unit	Lead-Free, 3 Preheating Zones, Dual Wave Soldering	/

03、Equipment Scale

Primary Inspection Equipment

NO.	Equipment	Brand	Equipment	Equipment	Process Capability	Production Speed / Capacity
1	3D AOI Inspection System	YAMAHA	YSi-V	2 units	Typical defects, solder balls, foreign objects, barcode errors, misplacement, cold solder joints detection rate	/
2	2D AOI Inspection System	劲拓	JTA-518	3 units	Typical defects, solder balls, foreign objects, barcode errors, misplacement, cold solder joints detection rate	/
3	SPI Solder Paste Inspection System	思泰克	S8030	5 units	Automatic detection of common printing defects such as insufficient solder paste and missing print (stencil printing defects)	/

03、 Equipment Scale

Primary Production Equipment



**High-Speed SMT Pick-and-Place Machine
YAMAHA YSM20R**
Component range:
0201–55 × 100 mm
PCB size: 810 × 490 mm



**High-Speed Multi-Function Pick-and-Place Machine
YAMAHA YSM10**
Component range: 03015–55 × 100 mm
PCB size: 510 × 460 mm



**High-Speed SMT Pick-and-Place Machine
YAMAHA F8S**
Component range:
0201–33 mm
PCB size: 510 × 381 mm



**High-Speed SMT Pick-and-Place Machine
YAMAHA G5S**
Component range: 03015–large components
PCB size: 1200 × 510 mm

03、Equipment Scale

Primary Production Equipment



Fully Automatic Solder Paste Printer 德森1008

0.3 mm pitch IC, 01005 and above chip components (R/C)
PCB size: 460 × 340 mm



8-Zone Lead-Free Reflow Soldering Oven 劲拓

JTE-800
Lead-Free, 8 Upper / 8 Lower (16 Zones Total)



10-Zone Lead-Free Reflow Soldering Oven 劲拓

TEA-1000D
Lead-Free, 10 Upper / 10 Lower (16 Zones Total)



Lead-Free Dual Wave Soldering Machine

HBE-350
Lead-Free, 3 Preheating Zones, Dual Wave Soldering

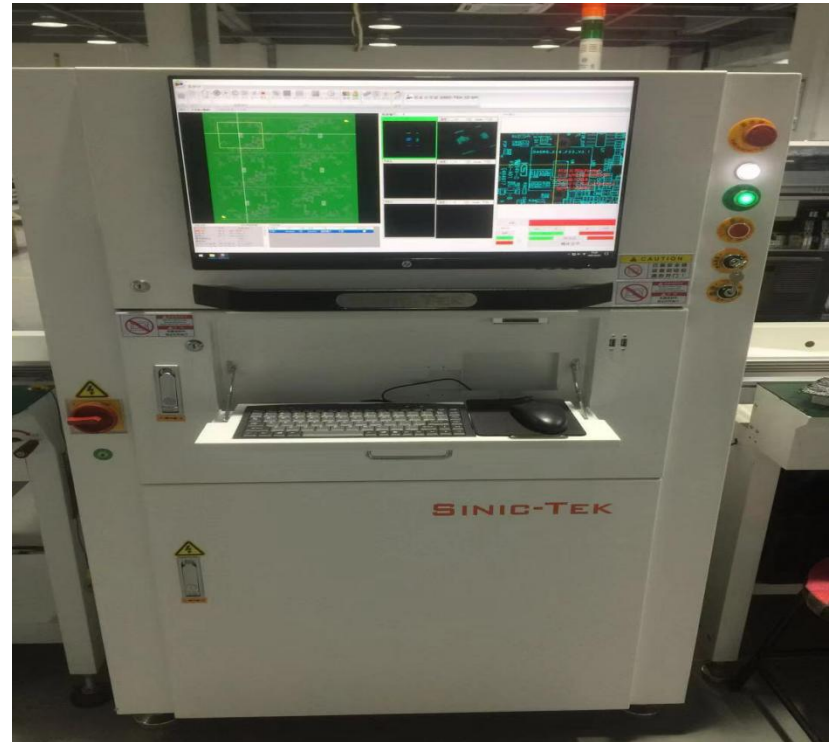
03、 Equipment Scale

Primary Inspection Equipment



YAMAHA 3D AOI Automatic Inspection Machine

Routine defect inspection with high detection rates for solder balls, foreign matter, barcode issues, multiple components, and false soldering.



SPI Solder Paste Automatic Inspection Machine

Scientific analysis of large datasets to accurately identify defect trends, enabling early detection of root causes and effective quality control and improvement.

03、Equipment Scale

Primary Inspection Equipment



劲拓 2D AOI Automatic Inspection Machine

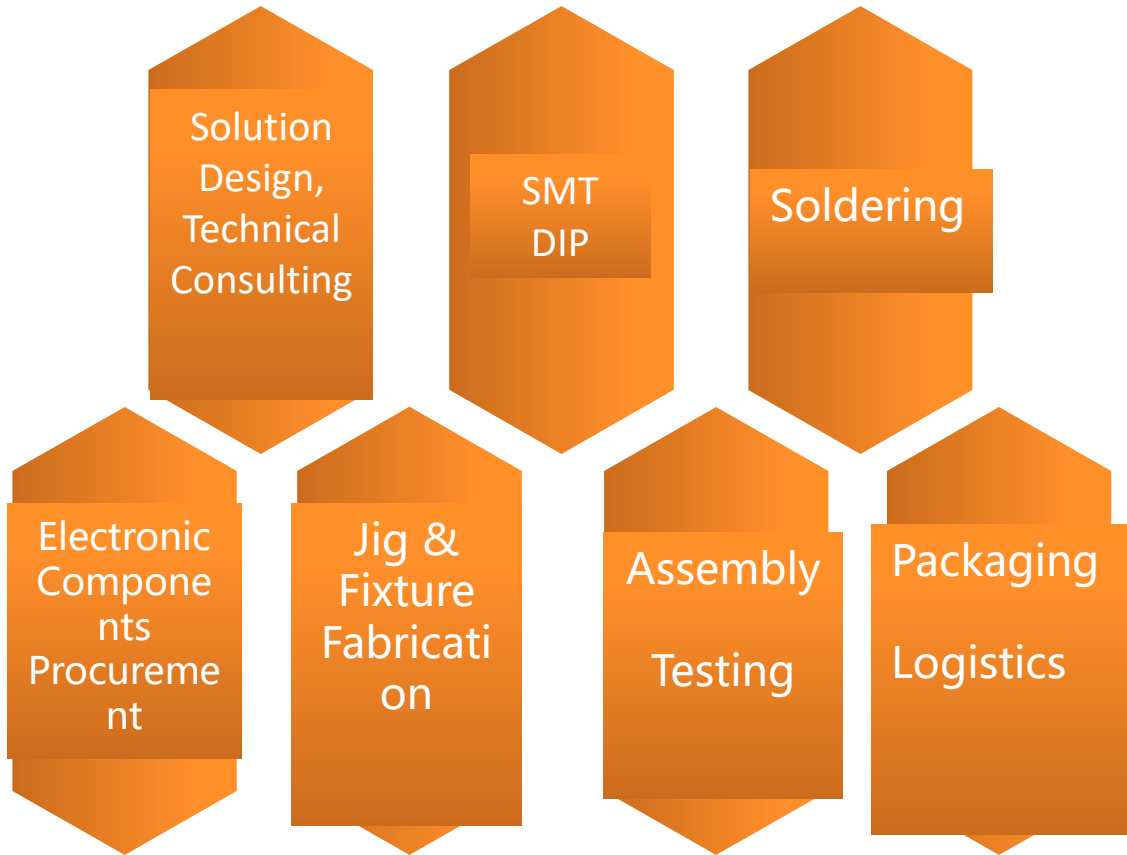
Routine defect inspection with high detection rates for solder balls, foreign matter, barcode issues, multiple components, and false soldering.



First Article Inspection System

Stable and reliable, prevents errors and omissions, with strong traceability.

04、 Service Scope



- Adopting a diversified strategy to meet customers' one-stop service needs.
- A professional DFM design team providing tailored solutions for customers.
- Customer-centric, enabling rapid manufacturing and delivery.

05、 Process Capabilities

SMT Component Specifications	SIZE	Minimum component size (in)	0201
		Maximum size (mm)	$45*45 < \text{SIZE} \leq 68*68$
		Component height (mm)	$T > 25.4$
	QFP / SOP / SOJ / IC / Pin Header, etc.	Minimum pin pitch (mm)	Pitch=0.3
	CSP、 BGA	Minimum BGA ball pitch (mm)	$0.4 \leq \text{Pitch} < 0.5$
PCB Process	Standard FR4, FPC, Rigid-Flex PCB, Metal Core PCB (MCPCB)		

>>> Process Capabilities

We provide flexible manufacturing capabilities to meet a wide range of PCB assembly requirements.

Process Type	Item	Parameter	Specification (mm)
 <p>SMT Assembly PCB Specifications</p>	Board Size (L*W)	Min.	$L < 50$ or $W < 30$
		Max.	$450 < L \leq 800$ or $350 < W \leq 400$
	Board Thickness (T)	Min.	$T < 0.8$
		Max.	$T > 5$
 <p>DIP Assembly PCB Specifications</p>	Board Size (L*W)	Min.	$L < 50$
		Max.	$500 < L \leq 1000$ or $100 < W \leq 400$
	Board Thickness (T)	Min.	$T < 0.8$
		Max.	$T > 5$



Note: Custom sizes and special requirements are available upon request.

06、 Application Areas



Industrial Control



Power Equipment



Aerospace



Military Products



Healthcare / Medical Devices



07、 Our Advantages

01: Integrated Synergy Advantage

02: Flexible Manufacturing

03: Fast Delivery

04: Quality Assurance

05: One-Stop Service

07、 Our Advantages

Type	Quantity		
	<100 pcs	101-1000pcs	>1000 pcs
Lead Time	1-2 days completion	≥2 days lead time, 3 days completion	≥3 days lead time, daily fixed-quantity production and shipment available based on customer requirements

Six control gates to ensure stable quality and customer satisfaction.



08、 Contact Us



Local Address

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9am to 8pm CST

Customer Service & Technical Support

Send 7SEtronic An Email

Please email our Customer Service team directly: info@7setronic.com

Plases contact our after-sale service if any quality issue:

cs@7setronic.com

24/5 Live chat now available


Direct, quick and easy live customer support

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THANK YOU

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 <http://7setronic.com/>

